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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/621,879	07/17/2003	Mona M. Eissa	TI-28394.1	3091	
23494	7590 04/14/2005		EXAMINER		
TEXAS INSTRUMENTS INCORPORATED			CHEN, KIN CHAN		
P O BOX 65	5474, M/S 3999				
DALLAS, T	CX 75265		ART UNIT	PAPER NUMBER	
			1765	<del></del>	
			DATE MAILED: 04/14/2005		

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)			1176
	10/621,879	EISSA, MONA	М.		
Office Action Summary	Examiner	Art Unit			
	Kin-Chan Chen	1765	<u> </u>		
<ul> <li>The MAILING DATE of this communication app</li> <li>Period for Reply</li> </ul>	ears on the cover sheet with the c	orrespondence a	address -		
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earmed patent term adjustment. See 37 CFR 1.704(b).	i6(a). In no event, however, may a reply be time within the statutory minimum of thirty (30) days ill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	nety filed s will be considered tin the mailing date of this D (35 U.S.C. § 133).	nely. communica	ation.	
Status					
<ol> <li>Responsive to communication(s) filed on</li> <li>This action is FINAL. 2b)∑ This</li> <li>Since this application is in condition for alloware closed in accordance with the practice under E</li> </ol>	action is non-final. ace except for formal matters, pro		he merits	s is	
·	x parte Quayle, 1933 O.D. 11, 40	.G. 213.			
	vn from consideration. r election requirement. r. epted or b)□ objected to by the l				
Applicant may not request that any objection to the care Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Ex	ion is required if the drawing(s) is ob	ected to. See 37	CFR 1.12		
Priority under 35 U.S.C. § 119					
12) Acknowledgment is made of a claim for foreign  a) All b) Some * c) None of:  1. Certified copies of the priority documents  2. Certified copies of the priority documents  3. Copies of the certified copies of the priority application from the International Bureau  * See the attached detailed Office action for a list	s have been received. s have been received in Applicati rity documents have been receive u (PCT Rule 17.2(a)).	on No ed in this Nation	al Stage		
Attachment(s)  1) Notice of References Cited (PTO-892)  2) Notice of Draftsperson's Patent Drawing Review (PTO-948)  3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date 071703.	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal F 6) Other:	ate	PTO-152)		

## **DETAILED ACTION**

## Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 22, 25, 26 and 29 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lee (U.S. 6,162,671).

Lee teaches etching TaN or TiN during the semiconductor device processing, using combining hydrofluoric acid and hydrogen peroxide in deionized water, applying solution in the presence of photoresist (col. 5, lines 39-42, 54; col. 6, lines 27-28; also col. 10, lines 45-50). Lee teaches that the hydrofluoric acid has a concentration in the range of 50% (col. 6, line 32), which is very close to 49% of the instant claim. Since the prior art range is close enough that it would be obvious that one skilled in the art would have expected it to have the same properties. Lee teaches that hydrogen peroxide may have a concentration of 1% to 36%, which encompasses the claimed range (see col. 6, lines 30-31).

Lee teaches etching solution is used at a temperature of 20 °C to 70 °C (socalled room temperature in the instant claim 22), see col. 6, lines 36-37. Art Unit: 1765

As to claim 26, Lee teaches etching solution is used at a temperature of 20 °C to 70 °C, which encompasses the claimed range, see col. 6, lines 36-37.

3. Claims 23, 24, 27, and 28 are rejected under 35 U.S.C. 103(a) as being unpatentable over Lee (U.S. 6,162,671) as evidenced by Kwag et al. (US 6,232,228), Kogure et al. (US 5,250,471).

Lee teaches etching TaN or TiN during the semiconductor device processing, using combining hydrofluoric acid and hydrogen peroxide in deionized water, applying solution in the presence of photoresist (col. 5, lines 39-42, 54; col. 6, lines 27-28; also col. 10, lines 45-50). Lee teaches that the hydrofluoric acid has a concentration in the range of 50% (col. 6, line 32), which is very close to 49% of the instant claim. Since the prior art range is close enough that it would be obvious that one skilled in the art would have expected it to have the same properties. Lee teaches that hydrogen peroxide may have a concentration of 1% to 36%, which encompasses the claimed range (see col. 6, lines 30-31).

Lee teaches etching solution is used at a temperature of 20 °C to 70 °C (so-called room temperature), see col. 6, lines 36-37.

Lee teaches etching solution is used at a temperature of 20 °C to 70 °C, which encompasses the claimed range, see col. 6, lines 36-37.

Claims 23, 24, 27, and 28 differ from Lee by specifying various compositions (such as a volume ratio greater than 1:1:20 of HF: $H_2O_2$ : deionized water in claims 23 and 27; a volume ratio greater than 2:1:21 of HF: $H_2O_2$ : deionized water in claims 24

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and 28) However, same were known to be result effective variables and commonly determined by routine experiment. The process of conducting routine experimentations (optimizations) so as to produce an expected result is obvious to one of ordinary skill in the art. In the absence of showing criticality or new, unexpected results, which is different in kind and not merely in degree from the results of the prior art, it is the examiner's position that a person having ordinary skill in the art at the time of the claimed invention would have found it obvious to modify Lee by performing routine experiments by using various compositions to obtain optimal result, MPEP 2144.05 II. See Kwag et al. (US 6,232,228; col. 16, lines 65-67) and Kogure et al. (US 5,250,471; col. 2, lines 54-59) in the record as evidences.

4. Claims 22-29 are rejected under 35 U.S.C. 103(a) as being unpatentable over Kwag et al.(US 6,232,228) as evidenced by Lee (U.S. 6,162,671) and Kogure et al. (US 5,250,471).

Kwag teaches a method for etching copper and dielectric materials (such as silicon nitride, TEOS) using an etching solution of a mixture of one oxidant (e.g., hydrogen peroxide), one enhancer (e.g., HF) and a buffer solution (e.g., deionized water). The etching solution may be applied in the presence of photoresist. The temperature in a range form 20 to 90 °C may be used, which encompasses the claimed temperature or range (claims 22 and 26). See col. 4, lines 2-25 and col. 5, lines 27-43; col. 8, lines 15-18; col. 11, line 40.

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Kwag is not particular about the concentrations of HF and hydrogen peroxide being used in the process. Hence, it would have been obvious to one with ordinary skilled in the art to use commonly available concentrations of HF and hydrogen peroxide as instantly claimed, see Lee (U.S. 6,162,671), in the aforementioned paragraph as evidence.

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The instant claims differ from Kwag by specifying various volume ratios of hydrofluoric acid: hydrogen peroxide: water (such as a volume ratio greater than 1:1:20 of HF:H<sub>2</sub>O<sub>2</sub>: deionized water in claims 23 and 27; a volume ratio greater than 2:1:21 of HF:H<sub>2</sub>O<sub>2</sub>: deionized water in claims 24 and 28). However, Kwag teaches that the etch properties can be easily changed by adjusting the etching composition. The etchant composition is known to be a result-effective variable. In the absence of showing criticality or new, unexpected results, which is different in kind and not merely in degree from the results of the prior art, it is the examiner's position that a person having ordinary skill in the art at the time of the claimed invention would have found it obvious to modify Kwag by using various compositions and determine the suitable volume ratio through routine experimentation in order to obtain the best etched product achievable. MPEP 2144.05 II. Also see Kogure et al. (US 5,250,471; col. 2, lines 54-59) in the record as evidences.

## Conclusion

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5. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Kogure et al. (US 5,250,471; col. 2, lines 54-59) teaches that the mixing ratio of the etchant have close relation with etching rate and etching amount.

6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Kin-Chan Chen whose telephone number is (571) 272-1461. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on (571) 272-1465. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

April 12,2005

Kin-Chan Chen Primary Examiner Art Unit 1765

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